**Product / Process Change Notice**

**Parts Affected:**

350mW Zener diodes manufactured in the SOT-23 case as shown below:

CMPZ4678 thru CMPZ4717

**Extent of Change:**

Addition of new wafer fab.

**Reason for Change:**

As part of Central Semiconductor’s supply chain risk mitigation initiative, and in an effort to ensure undisrupted product supply, an additional wafer fabrication site is being added for the referenced product families.  Product specifications, quality and reliability are not impacted by this addition.

**Effect of Change:**

This addition does not affect the fit, form or function of the devices.

**Qualification:**

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| --- | --- | --- |
| **Test** | **Condition** | **Failure rate** |
| **Resistance to Solder Shock** | T =260°C ±5°C Dwell time = 10 sec. **JESD22-B106** | 0/77 |
| **High Temperature Storage Life/ bake test.** | 150°C (-0/+10)°C, 1000 hours. **JESD22-A103** | 0/77 |
| **Temperature Cycling** | T= -65°C to +150°C 1000 cycles. Dwell time = 15 min. **JESD22-A104** | 0/77 |
| **High Temperature Reverse Bias (HTRB)** | T=125°C, t=1000 hours, VR=VZ **JESD22-A108** | 0/77 |
| **Highly Accelerated Temperature and Humidity Stress Test (HAST)** | T = 130°C, RH = 85%, P = 33.3 psia, and t = 96 hours. Bias conditions per device specification sheet. **JESD22-A110** | 0/77 |
| **Accelerated Moisture Resistance Unbiased Autoclave** | Temperature = 121°C ± 2°C; relative humidity = 100%; vapor pressure = 29.7 psia (15psig). t=96 hours **JESD22-A102** | 0/77 |

**Effective Date of Change:**

Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact your salesperson or manufacturer’s representative for samples.

As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor’s Product/Process Change Notification (PCN).

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| Company Name: |  |
| Address: |  |
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| Printed Name: |  |
| Title: |  |
| Signature: |  |
| Date: |  |